

Synopsys Demonstrates Leadership in AI-Powered Engineering at 2026 DAC Chips to Systems Conference

What's New: At the 2026 DAC Chips to Systems Conference, Synopsys is showcasing its latest silicon-to-systems innovations in agentic AI and advanced silicon design technologies that help customers accelerate AI-powered product development with greater quality, efficiency, precision, and scale from concept to production.

Announcements:

- **Synopsys and NVIDIA unveiled new, fully autonomous, long-running agentic capabilities** for chip design and electronics system design, powered by Synopsys AgentEngineer™ technology, enabled with NVIDIA Nemotron, NVIDIA's accelerated computing platform, and secured by NVIDIA OpenShell runtime. [Read the Synopsys press release to learn more.](#)
- **Synopsys advances agentic AI chip design with AMD and Microsoft**, introducing the first autonomous EDA workflows on Microsoft Discovery to accelerate engineering from specification to silicon. [Read the Synopsys press release to learn more.](#)
- **Synopsys and Intel Foundry expanded their collaborations** to advance design enablement for Intel 14A process technology, including certified AI-powered EDA flows, integrated multiphysics analysis, and a broad IP portfolio. [Read the Synopsys press release to learn more.](#)
- **Synopsys joins NVIDIA and industry leaders in the Open Secure AI Alliance.** Learn more: <https://blogs.nvidia.com/blog/open-secure-ai-alliance>

Engage with Synopsys at the 2026 DAC Chips to Systems Conference

Attendees can visit Synopsys booth #631 to experience live demonstrations showcasing how agentic AI, multiphysics-aware design, and advanced simulation technologies are helping engineers accelerate innovation from silicon to systems. Synopsys experts will also participate in technical sessions exploring advancements in AI, emulation and prototyping, memory architectures, and quantum-enabled design. For a complete list of Synopsys sessions and activities at 2026 DAC Chips to Systems Conference, visit the [Synopsys DAC 2026 event page](#).

Featured Booth Demonstrations Include:

- **Re-engineering EDA With Agentic AI Teams**
See how teams of specialized AI agents can autonomously orchestrate chip design, verification, and debug workflows to accelerate coverage closure, optimize PPA targets, and improve engineering productivity.
- **Multiphysics Fusion: Accelerating AI and Multi-Die Innovation**
Discover how integrated Synopsys and Ansys technologies combine AI-powered design, simulation, and signoff analysis to address power, thermal, signal integrity, and reliability challenges across advanced-node, multi-die, and photonic systems.
- **Multiphysics Simulation and AI-Driven Engineering**
Explore unified simulation and analysis workflows spanning chip, package, board, and [cooling-system design](#), including AI-driven optimization techniques that help engineers evaluate complex system interactions and accelerate design convergence.

Additional assets available online: